



US00D408014S

United States Patent [19]

Lai et al.

[11] Patent Number: **Des. 408,014**

[45] Date of Patent: ****Apr. 13, 1999**

[54] **HIGH DENSITY ELECTRICAL CONNECTOR**

5,066,240	11/1991	Verdun	439/181
5,104,326	4/1992	Smith et al.	439/95
5,547,398	8/1996	Ichikawa et al.	439/607

[75] Inventors: **Chi-Yi Lai; Kun-Tsan Wu**, both of Tu-Chen, Taiwan

[73] Assignee: **Hon Hai Precision Ind. Co., Ltd.**, Taipei Hsien, Taiwan

[**] Term: **14 Years**

Primary Examiner—Alan P. Douglas
Assistant Examiner—Lavone D. Tabor

[21] Appl. No.: **29/078,733**

[22] Filed: **Oct. 30, 1997**

[57] **CLAIM**

The ornamental design for a high density electrical connector, as shown.

[30] **Foreign Application Priority Data**

May 30, 1997 [TW] Taiwan 86304704

[51] **LOC (6) Cl.** **13-03**

[52] **U.S. Cl.** **D13/147**

[58] **Field of Search** D13/146, 147;
439/79-83, 95, 101, 108, 181, 607-610,
620

DESCRIPTION

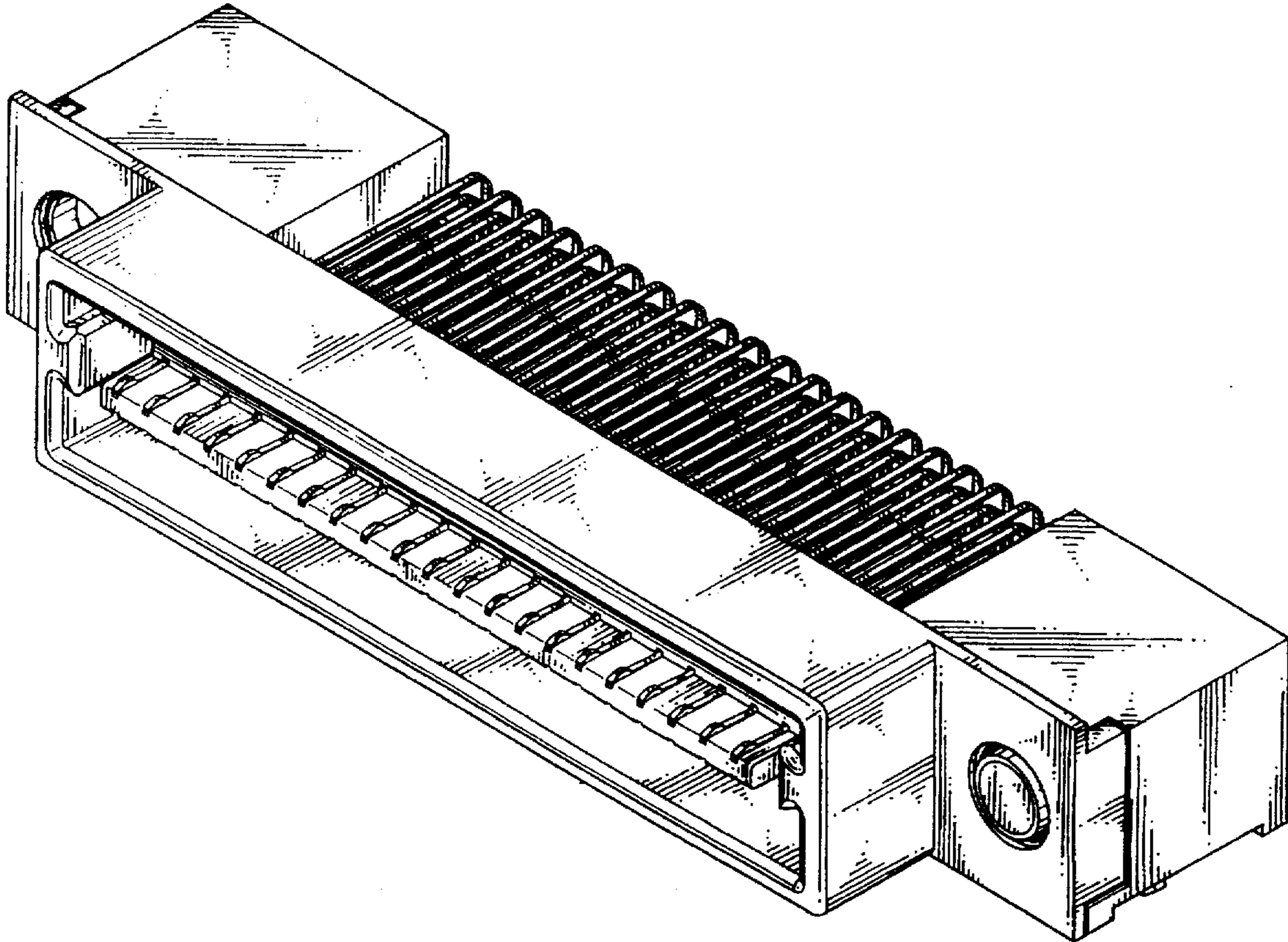
FIG. 1 is a perspective view of a high density electrical connector showing our new design;
FIG. 2 is a front elevational view thereof;
FIG. 3 is a rear elevational view thereof;
FIG. 4 is a left side elevational view thereof;
FIG. 5 is a right side elevational view thereof;
FIG. 6 is a top plan view thereof; and,
FIG. 7 is a bottom plan view thereof.

[56] **References Cited**

U.S. PATENT DOCUMENTS

D. 313,007 12/1990 Nakamura D13/147

1 Claim, 7 Drawing Sheets



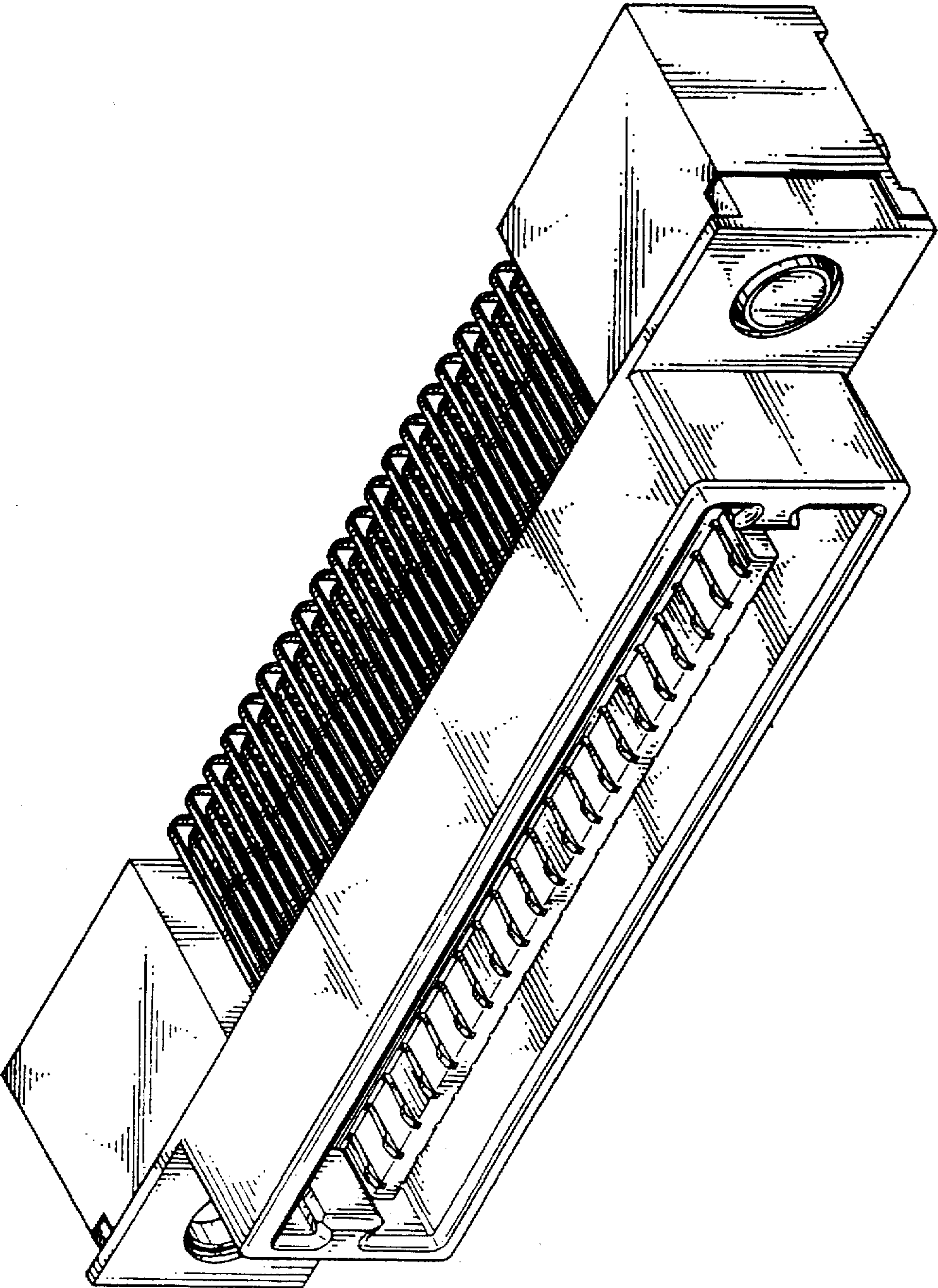


FIG.1

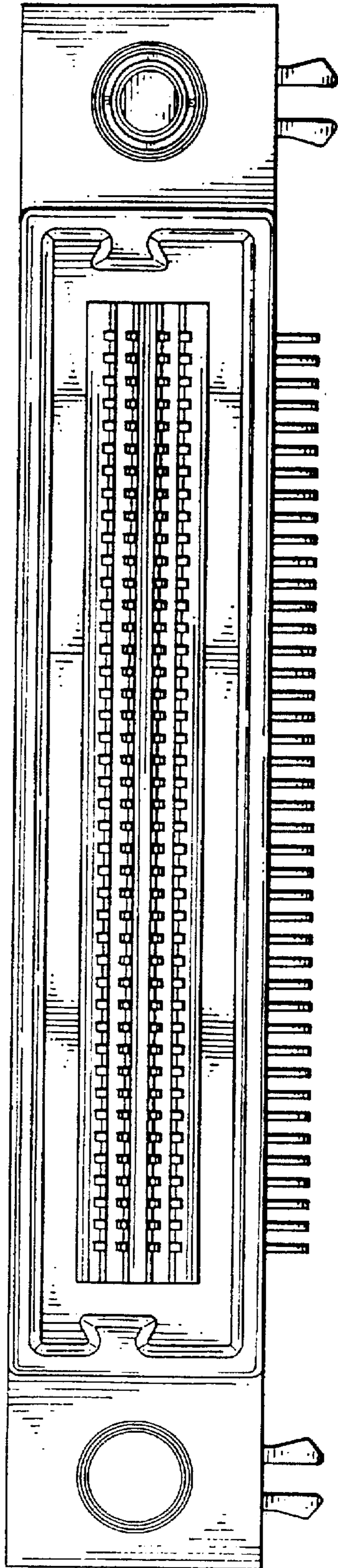


FIG. 2

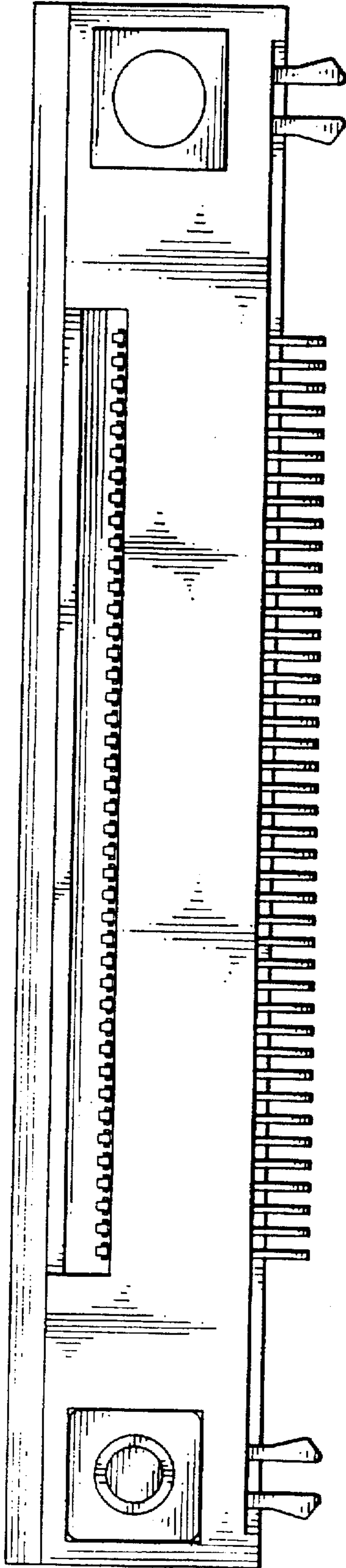


FIG. 3

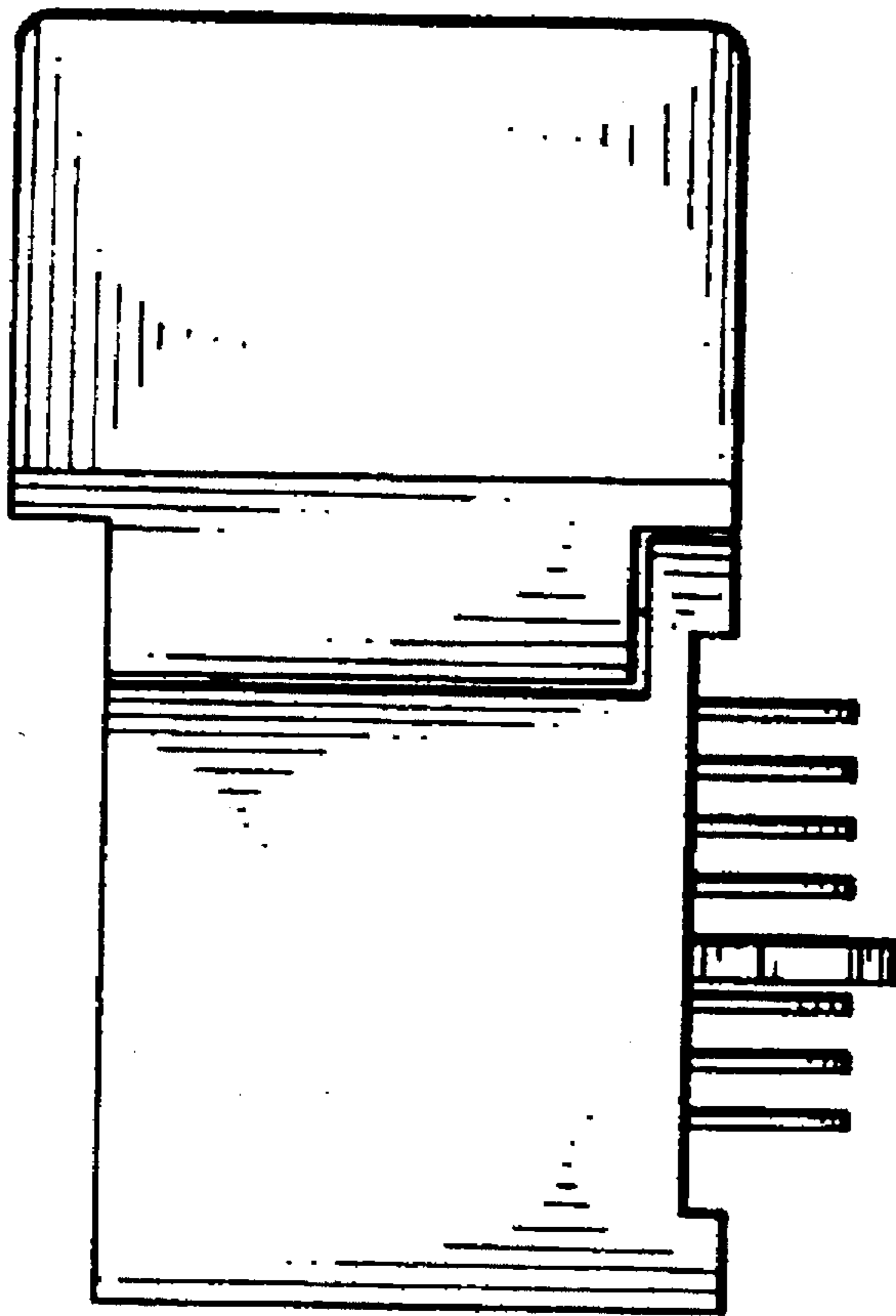


FIG. 4

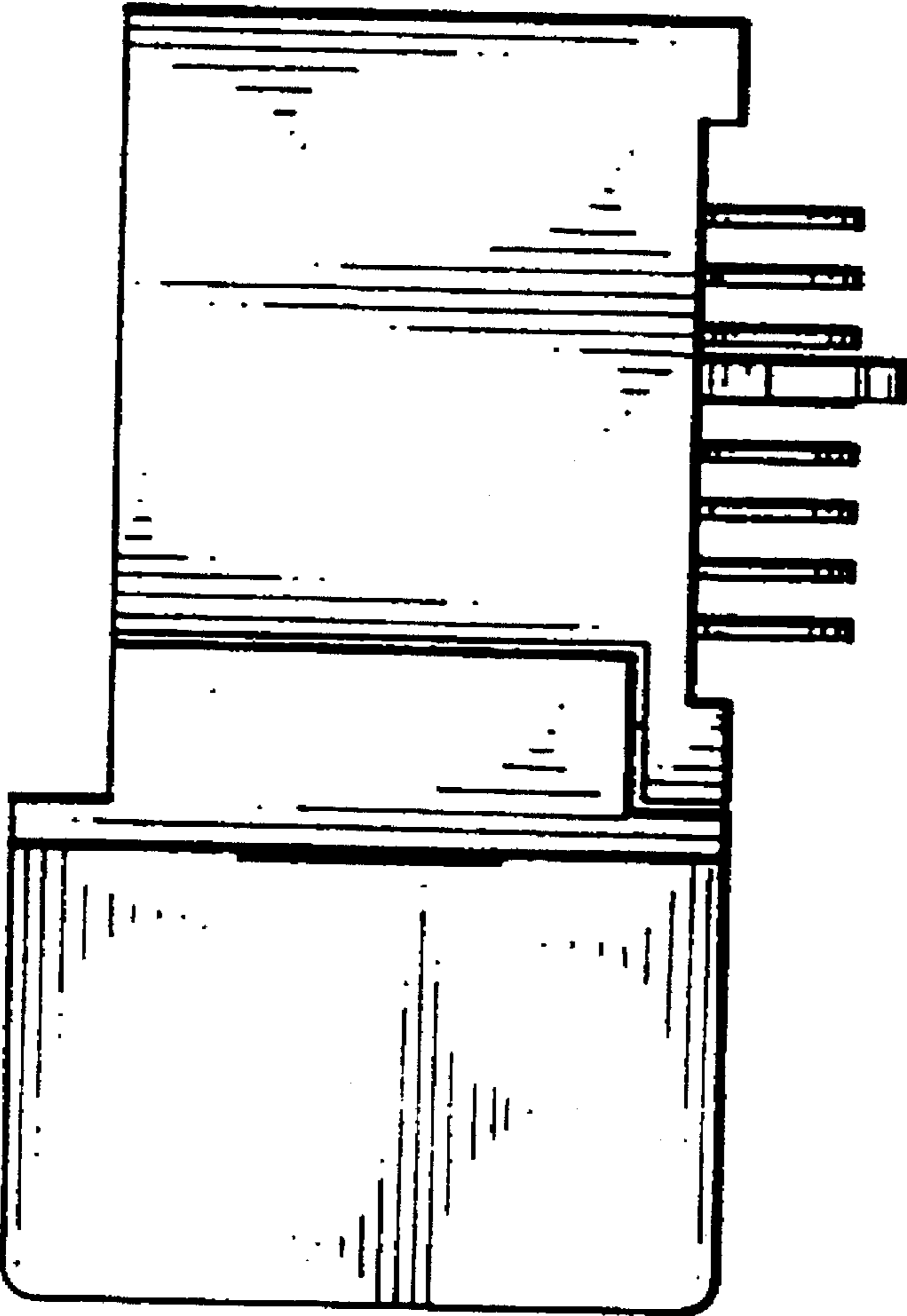


FIG. 5

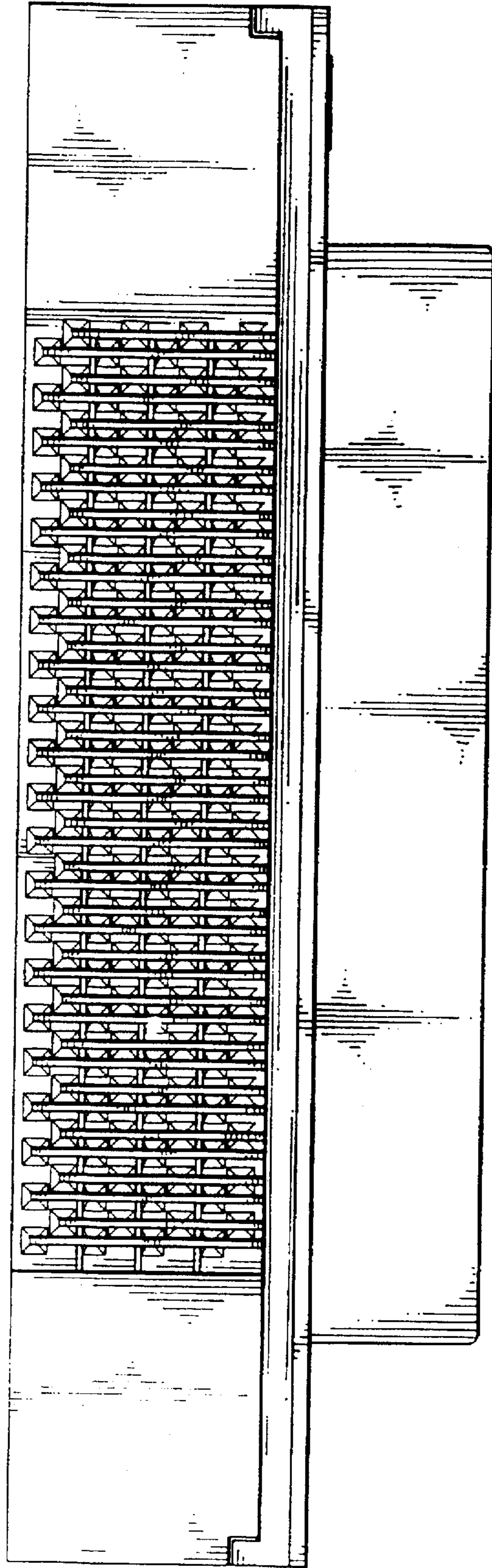


FIG. 6

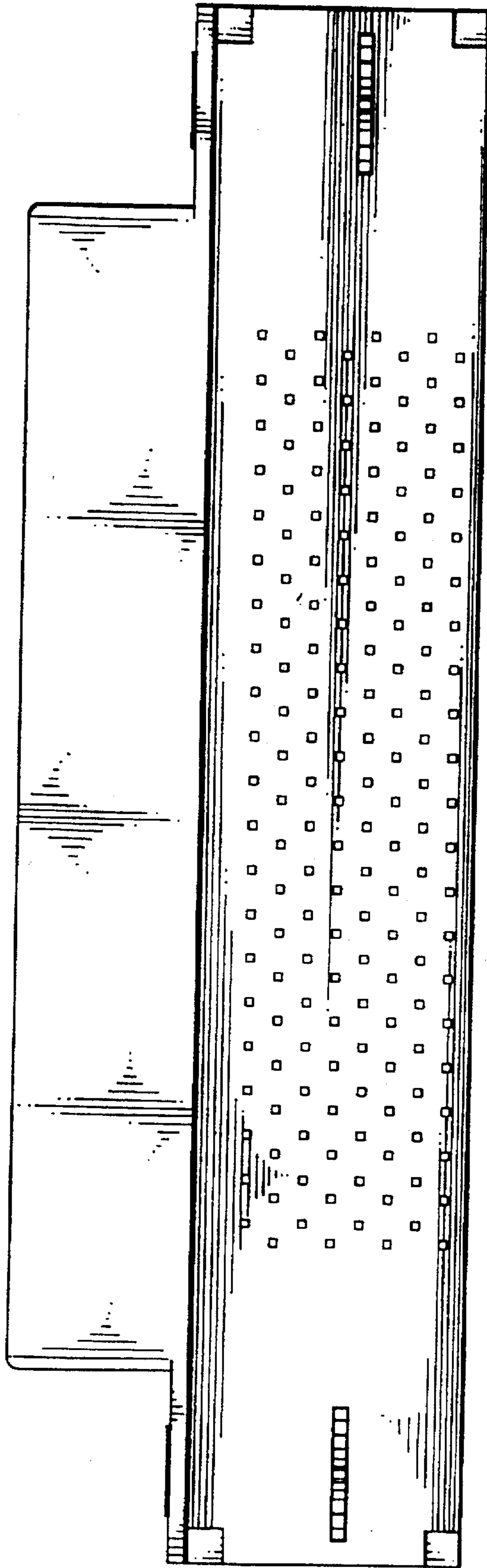


FIG. 7